[LAST - [10770167, sop;1] [] [] [] [] [] [] [] [] [] [1.61 1.01
<u>이러워의 #한당[위반]#</u>		121
D Diafts	- pove ga	
⇔ 2a Active	Dis Als Astria USPAT USOCR	P fine
1 12 L1: (2) "20040000428"	044205820 [cr] [("4004195" "44415025" "4593342" 748120	ر (1990-1997 1
L2: (2) (3344337) PN		70 (1.4914001 (1.4942070 (1.4902410 (1.4907950 (
" NRD32100000" (N 10e)	a de Service de Contra de logo fin fau fir effic.	Hirrant VSAL Derriquial Class Jacobses

8			issue Date	Pages	Title	Current OR	Current XRef	Retrieval Clas	invettor
F		US 5783862 A	19980721	5	Electrically conductive thermal interface	257/714	165/104,17 165/185		Deeney, Jeffrey L
**************************************	f	US 5561323 A	19961001	10	Electronic package with thermally conductive support member having a	267 <i>1</i> 707	257/706; 257/E21.518		Andros, Frank E. et al.
**************************************	1	US 5522452 A	19960604	18	Liquid cooling system for LSI packages	165/286	165/104.33; 165/295;		Mizuno: Tsukasa et al.
- I	\cdots	US 5519936 A	19960528	8	Method of making an electronic package with a thermally conductive support	29/840	174/52.4; 174/52.5		Andros; Frank E. et al.
r	r	US 5499450 A	19960319	9	Method of manufacturing a multiple pin- heatsink device	29/890.03	165/185; 257/E23.105		Jacoby, John
	{:::::	US 5459352 A	19951017	12	Integrated circuit package having a liquid metal-aluminum/copper joint	257/724	257/713; 257/718;		Layton; Wilber T. et al.
г	г	US 5423376 A	19950613	6	Heat exchanger for electronic components and electro-technical	165/80.4	165/168; 165/185;		Julien: Jean-Noel et al
		US 5345107 A	19940906	26	Cooling apparatus for electronic device	257/717	165/185; 257/712;		Daikoku; Takehiro et el.
*** · · · ·		US 5269372 A	19931214	10	Intersecting flow network for a cold plate cooling system	165/80.4	165/185; 257/714;		Chu, Richard C. et al.
г	ព	US 5226471 A	19930713	8	Leak isolating apparatus for liquid cooled electronic units in a coolent	165/200	165/103; 165/104.33;		Stefani; Gary G
*** '	٢	US 5060844 A	19911029	7	Interconnection structure and test method	228/180.21	228/203; 228/215;		Behun; John R. et al.
r	г	US 4967950 A	19901106	6	Soldering method	228/180.22	228/193 228/254		Legg: Stephen P. et al.
г	г	US 4962416 A	19901009	6	Electronic package with a device positioned above a substrate by suction	257/722	257/783; 257/E23.063;		Jones; Alan L. et al.
г	٣	US 4942076 A	19900717	. 11	Ceramic substrate with metal filled via holes for hybrid microcircuits and	428/137	257/E23.067; 257/E23.19;		Panicker, Ramachandra M. P et al
г	c	US 4914551 A	19900403	7	Electronic package with heat spreader member	361/714	257/713; 257/717;		Anschel; Morris et al.
г		US 4512978 A	19860923	10	Apparatus for cooling high-density integrated circuit packages	165/104.33	165/46; 257/714;		Cutchaw, John M.
	r	US 4593342 A	19860603	5	Heat sink assembly for protecting pins of electronic devices	361/720	257/718, 257/720		Lindsay: Paul H.

NUN.